CLAIMS:

1. Method for detaching an electronic device from an adhesive tape on which the electronic device has been mounted, the method comprising the steps of:

positioning the electronic device over an abutment protrusion of an ejector assembly along a first axis, wherein the electronic device has a first edge and a second edge opposite to the first edge, and the abutment protrusion has a relatively fixed position on the ejector assembly along a second axis that is perpendicular to the first axis;

moving the abutment protrusion along the first axis to push the abutment protrusion against the electronic device adjacent to the first edge of the electronic device, so as to lift the first edge of the electronic device away from the adhesive tape;

sliding the electronic device and the ejector assembly relative to each other along the second axis while the electronic device is lifted by the abutment protrusion until the abutment protrusion is pushing against the electronic device adjacent to the second edge of the electronic device;

contacting the electronic device with an electronic device holder, and removing the electronic device from the adhesive tape with the electronic device holder.

2. Method as claimed in claim 1, wherein the ejector assembly includes an ejector cap and an opening on a surface of the ejector cap from which the abutment protrusion is projectable from inside a housing of the ejector cap along the first axis.

3. Method as claimed in claim 2, further including the step of generating a vacuum suction force from inside the ejector cap through the opening for retaining the adhesive tape on a top retaining surface of the ejector cap.

4. Method as claimed in claim 3, wherein a size of the opening is smaller than a size of the electronic device to prevent an electronic device being

received into the opening when the adhesive tape is retained on the top retaining surface by the vacuum suction force.

5. Method as claimed in claim 1, wherein the adhesive tape is supported and stretched on an adhesive tape mounting frame, and the adhesive tape mounting frame is in turn coupled to a positioning table, such that during the step of sliding the electronic device and the ejector assembly relative to each other, the positioning table moves the adhesive tape relative to the ejector assembly while the abutment protrusion and the ejector assembly are stationary.

6. Method as claimed in claim 1, wherein the ejector assembly is coupled to a driving system for moving the ejector assembly including the abutment protrusion together relative to the adhesive tape.

7. Method as claimed in claim 1, further comprising the step of actuating the abutment protrusion to push against the electronic device adjacent to the first edge at a starting offset between the first edge of the electronic device and the abutment protrusion, such starting offset being operative to initiate pre-peeling between the first edge of the electronic device and the adhesive tape.

8. Method as claimed in claim 7, wherein the abutment protrusion is raised to a pre-peeling elevation height which inclines the electronic device relative to the adhesive tape to initiate pre-peeling without an excessive bending of a second electronic adjacent to the electronic device, so as to avoid causing damage to the second electronic device.

9. Method as claimed in claim 8, wherein the abutment protrusion is lowered from the pre-peeling elevation height to a sliding elevation height prior to sliding the electronic device and the ejector assembly relative to each other, the abutment protrusion being maintained at the sliding elevation height during such sliding motion.

10. Method as claimed in claim 1, wherein when the abutment protrusion is pushing against the electronic device adjacent to the second edge, the

abutment protrusion is located at an ending offset between the abutment protrusion and the second edge, such that the electronic device is not completely peeled off from the adhesive tape at the end of the sliding motion.

11. Method as claimed in claim 10, further comprising the step of lowering the abutment protrusion away from the electronic device after the electronic device is contacted by the electronic device holder and the adhesive tape is peeled from the second edge of the electronic device, prior to the electronic device holder removing the electronic device from the adhesive tape.

12. Method as claimed in claim 1, wherein the electronic device holder contacts the electronic device at an electronic device holder offset between a center of the electronic device holder and a center of the abutment protrusion, such that the electronic device holder and the abutment protrusion are not aligned along the first axis.

13. Method as claimed in claim 1, further comprising the step of detecting whether the electronic device holder has failed to remove an electronic device from the adhesive tape, and if the electronic device remains on the adhesive tape, increasing the pre-peeling elevation height before sliding the electronic device and the ejector assembly relative to each other during a subsequent repeated attempt to detach the electronic device from the adhesive tape.

14. Method as claimed in claim 1, wherein the abutment protrusion comprises a narrow linear strip that is arranged in use to extend parallel to a width of the electronic device which is being detached.

15. Method as claimed in claim 14, wherein a span of the linear strip is equal to or slightly smaller than the width of the electronic device.

16. Method as claimed in claim 14, wherein a width of the linear strip is significantly small than a width of the electronic device to apply a localized force to lift a portion of the electronic device the linear strip is pushing against.

17. Method as claimed in claim 1, wherein the abutment protrusion has a tapered profile along the first axis such that a tip portion of the abutment protrusion is narrower than a base of the abutment protrusion.

18. Method as claimed in claim 1, wherein a tip of the abutment protrusion has a convex surface for pushing against the electronic device.

19. Method as claimed in claim 1, wherein a cross-section of the abutment protrusion along a width of the abutment protrusion is substantially rectangular.